

Connector for microSD™ Card (Push-push Type)

SCHA Series



Compact low-profile type most suitable for mobile phones.

For SD Memory Card

For microSD™ Card

For SIM Card 8pins

For W-SIM

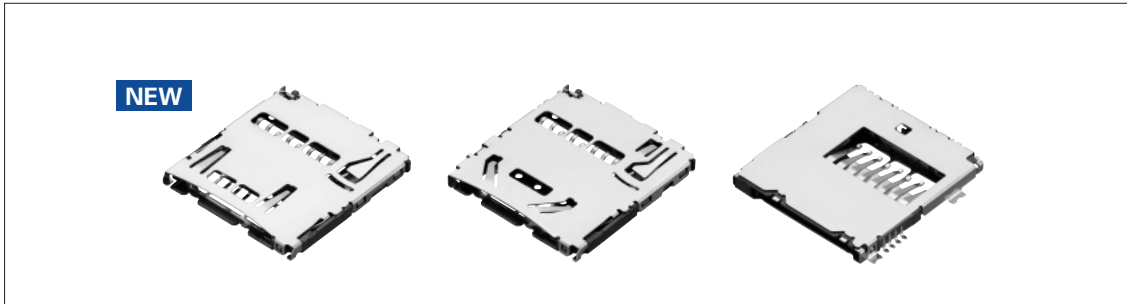
For Memory Stick Micro™

For Memory Stick™

Combine Type

For Compact Flash™

For CMOS Camera Module



Typical Specifications

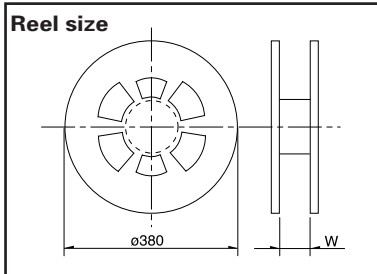
Items		Specifications	
Structure	Applicable media	microSD™ Card	
	Mounting type	Surface mounting type	
	Mounting style	Standard mount/ Reverse mount	
	Media ejection structure	Push-push type	
Performance	Operating temperature range	-20°C to +70°C	
	Voltage proof	500V AC 1minute	
	Insulation resistance (Initial)	1,000MΩ min.	
	Contact resistance (Initial)	Connector contacts	100mΩ max.
		Detection switch	500mΩ max.
Insertion and removal cycle	5,000cycles		

Product Line

Media ejection structure	Mounting system	Features	Stand-off (mm)	Packing system	Product No.	Drawing No.
Push-push type	Standard mount	With switch	0	Taping	SCHA4B0100	1
		With switches and fly-out protection.			SCHA4B0400	2
	Reverse mount	With switch			SCHA5B0200	3

Packing Specifications

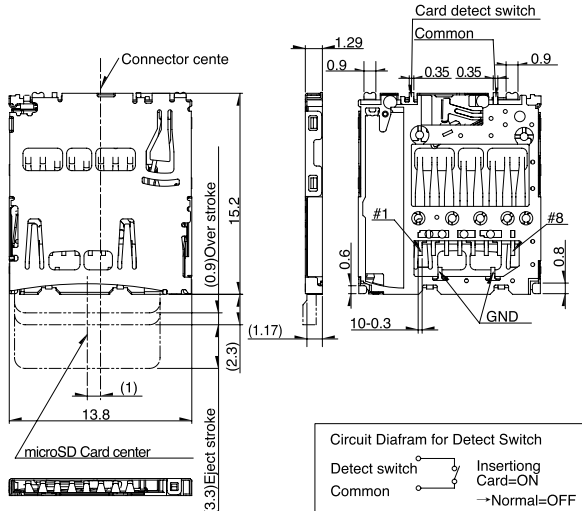
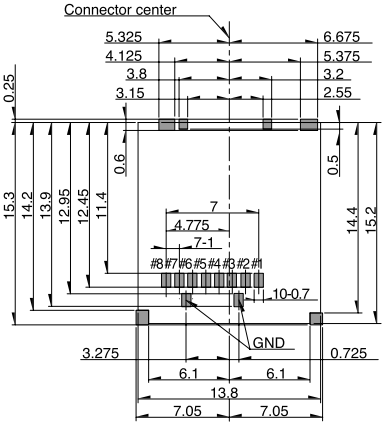
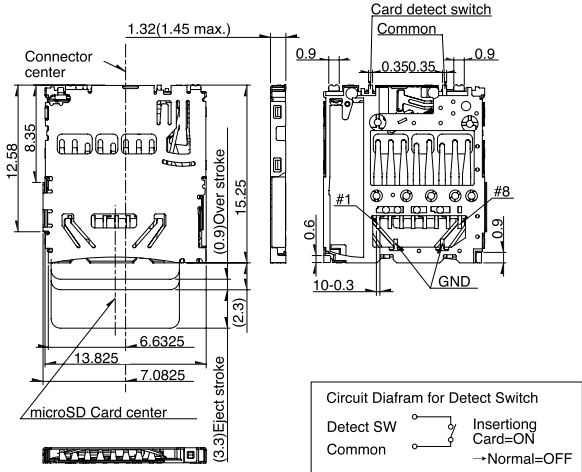
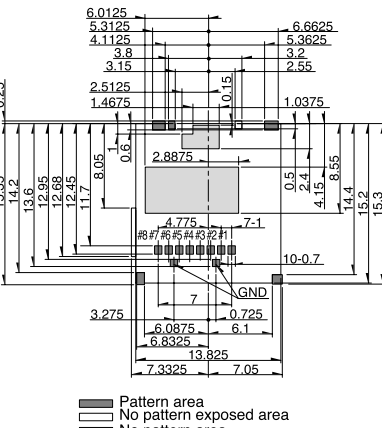
Taping Unit:mm



Product No.	Number of packages (pcs.)			Reel width W (mm)	Tape width (mm)	Export package measurements (mm)
	1 reel	1 case /Japan	1 case /export packing			
SCHA4B0100	2,000	6,000	12,000	24.4	24	403×403×249
SCHA4B0400						
SCHA5B0200	1,500	4,500	9,000			

Dimensions
Standard mount

Unit:mm

No.	Style	PC board mounting hole dimensions (Viewed from the mounting face side)																				
1	<p>With switch</p>  <table border="1" data-bbox="630 996 901 1108"> <thead> <tr> <th>PIN</th> <th>SD Mode</th> <th>PIN</th> <th>SD Mode</th> </tr> </thead> <tbody> <tr> <td>#1</td> <td>DAT2</td> <td>#5</td> <td>CLK</td> </tr> <tr> <td>#2</td> <td>DAT3/CD</td> <td>#6</td> <td>V_{SS}</td> </tr> <tr> <td>#3</td> <td>CMD</td> <td>#7</td> <td>DAT0</td> </tr> <tr> <td>#4</td> <td>V_{DD}</td> <td>#8</td> <td>DAT1</td> </tr> </tbody> </table> <p>Pin assignments</p>	PIN	SD Mode	PIN	SD Mode	#1	DAT2	#5	CLK	#2	DAT3/CD	#6	V _{SS}	#3	CMD	#7	DAT0	#4	V _{DD}	#8	DAT1	
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2	<p>With switches and fly-out protection.</p> 																					

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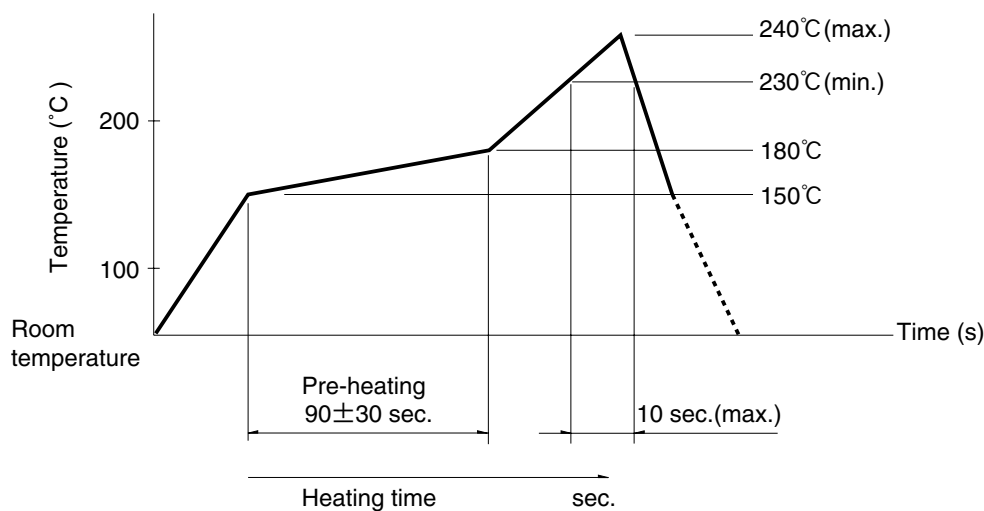
For Compact Flash™

For CMOS Camera Module

Soldering Conditions

Example of Reflow Soldering Condition (Reference)

1. Heating method: Double heating method with infrared heater.
2. Temperature measurement: Thermocouple 0.1 to 0.2 ϕ CA (K) or CC (T).
3. Temperature profile (Surface of products).



Cautions for using this product

1. When soldering terminals, there is a danger that load placed on the terminals may cause rattle, deformation or electrical degradation to occur depending on the conditions. Caution is therefore required.
2. Avoid use of water-soluble soldering flux, since it may corrode the product.
3. Check and conform to reflow soldering requirements under actual mass production conditions.
4. PC board warping may alter the characteristics. Please take this into consideration when designing patterns and layout.
5. The card specifications are provided by the above manufactures. Products by other manufactures may not be compliant with these specifications and are subject to change without prior notice.

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